

3D Chips (3D IC): Market Research Report

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Abstracts

This report analyzes the Global market for 3D Chips (3D IC) in US\$ Million.

Annual estimates and forecasts are provided for the period 2006 through 2015.

The report profiles 38 companies including many key and niche players such as Amkor Technology, GlobalFoundries, Inc., Hynix Semiconductor, Inc., International Business Machines Corporation, Intel Corporation, Micron Technology, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd., Sony Corporation, Tezzaron Semiconductor Corporation, Toshiba Semiconductors, and Ziptronix, Inc.

Market data and analytics are derived from primary and secondary research.

Company profiles are mostly extracted from URL research and reported select online sources.

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Heat
Complexity of Design
Lack of Clearly Defined Standards
Lack of Relevance Post Insertion
Supply Delay

3.PRODUCT INTRODUCTIONS/LAUNCHES

TierLogic Announces the Launch of 3D FPGA
Movidius Rolls Out 3D Chip for Smartphones
STMicroelectronics Unveils 3D IC Chip for Digital TV Applications
Applied Materials Launches Avila™ Technology
STMicroelectronics Launches 3D IC for Enhanced Audio in Portable Media Players
BeSang Unleashes 3D IC Technology to Enable Low Cost Solutions
Sound Design Technologies Rolls Out New 3D Chip Stacking Technology
Toshiba to Develop 3D NAND Flash Chip
NEC Develops New 3D Chip Stacked Flexible Memory for SoC
IMEC Introduces 3D SIC Technology
Aviza Technology Launches Versalis fxP

4.RECENT INDUSTRY ACTIVITY

CEA-Leti, SPTS Ally Over Next-Gen TSV Development
EVG, IME Collaborate for 3D-IC Integration Technologies
CMC, CMP, MOSIS Ally for 3D-IC Process
Elpida Collaborate with PTI, UMC for 3D-IC Integration Development
Leti, R3Logic Partner for 3D-IC Methodologies and Designs
NEC Electronics Merges with Renesas Technology
Advanced Technology Investment Company Acquires Chartered Semiconductor Manufacturing
ON Semiconductor Acquires Sound Design Technologies
SPP Acquires Key Assets of Aviza Technology
IBM Partners with ETH and EPFL to Co-Develop Eco-Friendly 3D Microchips
S.E.T and IMEC Collaborate to Develop Processes for 3D Integration
Industrial Technology Research Institute Collaborates with Applied Materials
EV Group and Applied Materials Collaborate to Develop Wafer Bonding Process for 3D IC
Soitec Collaborates with CEA-Leti for 3D Integration

Apple Acquires Stake in Imagination Technologies

Applied Materials Acquires Semitool

KLA- Tencor Acquires Stake in ICOS Vision Systems

Zoran Corporation Takes Over Let It Wave

SanDisk Enters into Collaboration with Toshiba for Rewriteable 3D Chip Development

BeSang Collaborates with National NanoFab Centre and Stanford NanoFab to Develop 3D IC

Singapore forms Novel Consortium to Boost 3D Adoption

DDD and Samsung Collaborate for Development of 3D Chips

5.FOCUS ON SELECT PLAYERS

Amkor Technology (US)

GlobalFoundries, Inc. (US)

Hynix Semiconductor, Inc. (South Korea)

International Business Machines Corporation (US)

Intel Corporation (US)

Micron Technology, Inc. (US)

Renesas Electronics Corporation (Japan)

Samsung Electronics Co., Ltd. (South Korea)

Sony Corporation (Japan)

Tezzaron Semiconductor Corporation (US)

Toshiba Semiconductors (Japan)

Ziptronix, Inc. (US)

6.GLOBAL MARKET PERSPECTIVE

Table 1. World Recent Past, Current & Future Analysis for 3D Chips (3D IC) Analyzed with Annual Sales Figures in US\$ Million for Years 2006 through 2015 (includes corresponding Graph/Chart)

III. COMPETITIVE LANDSCAPE

Total Companies Profiled: 38 (including Divisions/Subsidiaries - 40)

Region/CountryPlayers

The United States16

Canada

Japan

Europe

France

The United Kingdom

Rest of Europe

Asia-Pacific (Excluding Japan)

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